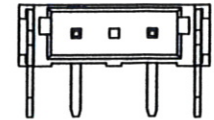
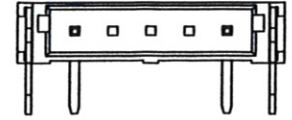


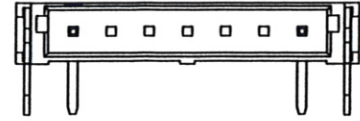
P/N:AD017320251X1(3Hole 2Pin)



P/N:AD017340251X1(5Hole 2Pin)



P/N:AD017360251X1(7Hole 2Pin)



REV	MODIFICATION	DATE	DRAW
A0	Release To S1103128	2011.03.23	Seven
A1	Release To ECN20130208	2013.02.27	Seven
A2	Release To ECN20150206	2015.02.11	Michelle

**RoHS Compliant**

Specification

- 1.Current Rating:1A AC/DC
- 2.Voltage Rating:600V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:1000MΩ Min.
- 5.Dielectric Withstanding Voltage:AC1800V/Minute
- 6.Operating Temperature:-25°C~+85°C

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Tab:Copper Alloy T=0.30mm
- 3.Contact Pin:Copper Alloy T=0.50mm

Finish:

- 1.Housing:Natural
- 2.Tab:Matte Tin Plated Over Nickel
- 3.Contact Pin:Matte Tin Plated Over Nickel

Part No.:AD017 XX 02 5 2 4 1

- Series
- 32:3Hole 2Pin
- 34:5Hole 2Pin
- 36:7Hole 2Pin
- No. Of Pin
- 02
- Packing
- 4:Tube
- Plating
- 2:Matte Tin Plated Over Ni
- Housing Material
- 5:HTN UL94V-0 Natural

36	12.00	18.00	14.40
34	8.00	14.00	10.40
32	4.00	10.00	6.40
Series	DIM.A	DIM.B	DIM.C

發行  
104.2.11  
文管中心

**金上達科技股份有限公司**  
GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED

PROJ.

TITLE: Wire To Board Wafer 4.00mm 90° DIP (3,5,7 Holes 2Pin) Single Row

APR. C.F.Liao 20150211

CHK. Abel 20150211

DRA. Michelle 20150211

PART NO. AD017XX025241

DWG NO. AD017XX025241

UNITS: mm

CUSTOMER DRAWING

SIZE: A4

SCALE 5:1

SHEET 1 / 2

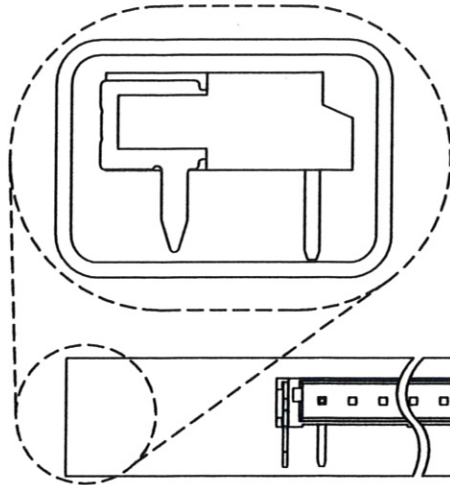
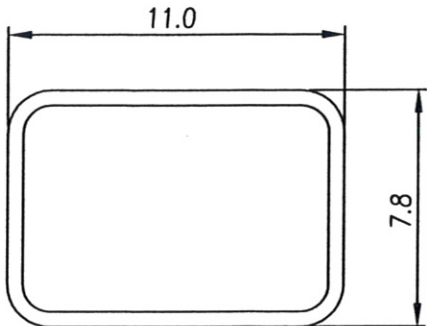
REV A2

**RECOMMENDED P.C.B LAYOUT**

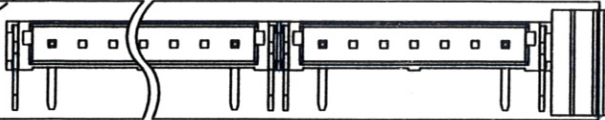
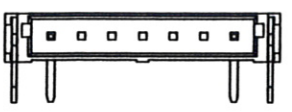
1 | 2 | 3 | 4 | 5 | 6 | 7 | 8

REV	MODIFICATION	DATE	DRAW
A0	Release To S1103128	2011.03.23	Seven
A1	Release To ECN20130208	2013.02.27	Seven
A2	Release To ECN20150206	2015.02.11	Michelle

**A2**  
 1. 拿出包裝管,管子料號:NT000000013C9(11.0x7.8x570mm) 2. 依圖所示,依序將產品裝入管內  
 先將包裝管後方塞上軟塞 各PIN數,每管數量參考右表:

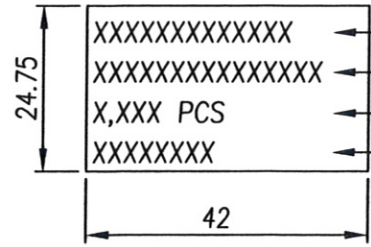
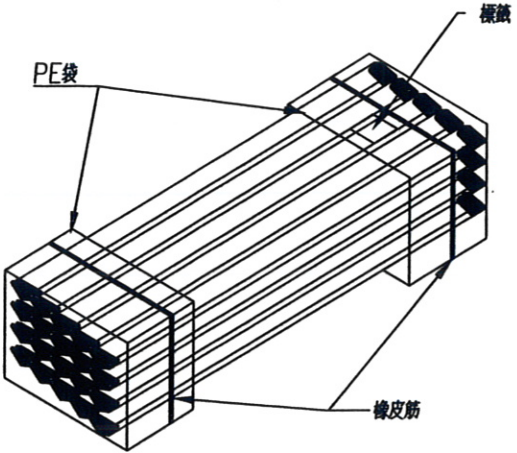


料號	數量
AD01732025241	54
AD01734025241	39
AD01736025241	30



3. 每5管一層,堆疊4層,共20管  
 每束前後端,用PE袋前後套住,用橡皮筋束緊(避免塞子脫落,成品損壞)

4. 依實際生產數量,辦理入庫  
 需於產品包裝外貼上標籤  
 標籤格式如右:



料號  
 品名  
 數量  
 製造日期(西元年/月/日)或入庫單單號



<b>金上達科技股份有限公司</b> GOLDENSUNDA TECHNOLOGY CO., LTD			
TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 4.00mm 90° DIP (3,5,7 Holes 2Pin) Single Row
.x± 0.35	x'± 2'	APR. C.F.Liao 20150211	PART NO. AD017XX025241
.xx± 0.25	.x'± 1'	CHK. Abel 20150211	DWG NO. AD017XX025241
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20150211	UNITS: mm
		SIZE: <b>A4</b>	CUSTOMER DRAWING
		SCALE: Free	SHEET 2 / 2
		REV: A2	

1 | 2 | 3 | 4 | 5 | 6 | 7 | 8

A

B

C

D

E

F

A

B

C

D

E

F